

Notification about Sealing Sticker on Packaging Box to Prevent Tampering with Products (MELSEC iQ-R/MELSEC iQ-F series)

■Date of Issue

November 2021 (Ver.C: February 2024)

■Relevant Models

FX5U-32MR/DS, FX5U-32MR/ES, FX5U-32MT/DS, FX5U-32MT/DSS, FX5U-32MT/ES, FX5U-32MT/ESS, FX5U-64MR/DS, FX5U-64MR/ES, FX5U-64MT/DS, FX5U-64MT/DSS, FX5U-64MT/ES, FX5U-64MT/ESS, FX5U-80MR/DS, FX5U-80MR/ES, FX5U-80MT/DS, FX5U-80MT/DSS, FX5U-80MT/ES, FX5U-80MT/ESS, FX5UC-32MR/DS-TS, FX5UC-32MT/D, FX5UC-32MT/DSS, FX5UC-32MT/DSS-TS, FX5UC-32MT/DS-TS, FX5UC-64MT/D, FX5UC-64MT/DSS, FX5UC-96MT/D, FX5UC-96MT/DSS, R00CPU, R01CPU, R02CPU, R04CPU, R04ENCPU, R08CPU, R08ENCPU, R16CPU, R16ENCPU, R32CPU, R32ENCPU, R120CPU, R120ENCPU

Thank you for your continued support of Mitsubishi Electric programmable controllers, MELSEC iQ-R and MELSEC iQ-F series.

To prevent tampering with products including software after shipment from the factory, a sealing sticker will be put on the packaging box. This contributes to enhance the product security.

There is no impact on the general specifications, performance specifications, functions, and external dimensions of products due to the change.

For the R00CPU, R01CPU, R02CPU, R04CPU, R04ENCPU, R08CPU, R08ENCPU, R16CPU, R16ENCPU, R32CPU, R32ENCPU, R120CPU, and R120ENCPU, the specifications of their packaging boxes were changed. For details, refer to the following technical bulletin.

 [Change in Packaging Box to Prevent Tampering with MELSEC iQ-R Series Products \(FA-A-0384\)](#)

1 DETAILS ON THE CHANGE

The sealing sticker will be put on the packaging box opening.

1.1 External Appearance and Specifications of the Sealing Sticker

The sealing sticker varies depending on the date of manufacture of each model.

The following shows the external appearance and specifications of sealing stickers.

Period of sticker application	External appearance	Dimensions	Specifications
December 2021 to February 2022		20mm × 40mm	<ul style="list-style-type: none"> The corporate logo is indicated on the sealing sticker. Transcription type stickers are used. After the sticker is removed, the letters "VOID" will remain on the packaging box.
March 2022 or after		25mm × 55mm	<ul style="list-style-type: none"> The corporate logo is indicated on the sealing sticker. Strong adhesive is used. After the sticker is removed, a trace of opening will remain on the packaging box.

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1.2 Specified Position of the Sealing Sticker on Each Packaging Box

The following shows the position of the sealing sticker on each packaging box for the models manufactured on or after March 2022. For the models manufactured on or before February 2022, the sealing sticker differs but the applied position on the packaging box is the same.

Relevant model	Position of sealing sticker on packaging box	
FX5U-32MR/DS, FX5U-32MR/ES, FX5U-32MT/DS, FX5U-32MT/DSS, FX5U-32MT/ES, FX5U-32MT/ESS, FX5U-64MR/DS, FX5U-64MR/ES, FX5U-64MT/DS, FX5U-64MT/DSS, FX5U-64MT/ES, FX5U-64MT/ESS, FX5U-80MR/DS, FX5U-80MR/ES, FX5U-80MT/DS, FX5U-80MT/DSS, FX5U-80MT/ES, FX5U-80MT/ESS, FX5UC-32MR/DS-TS, FX5UC-32MT/ D, FX5UC-32MT/DSS, FX5UC-32MT/ DSS-TS, FX5UC-32MT/DS-TS, FX5UC-64MT/D, FX5UC-64MT/DSS, FX5UC-96MT/D, FX5UC-96MT/DSS	Left side of the lid 	Bottom 
R00CPU, R01CPU, R02CPU	Left side of the lid 	
R04CPU, R08CPU, R16CPU, R32CPU, R120CPU	Left side of the lid 	

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Relevant model	Position of sealing sticker on packaging box	
R04ENCPU, R08ENCPU, R16ENCPU, R32ENCPU, R120ENCPU	Left side of the lid	Bottom
		

2 RELEVANT MODELS

Product	Model
MELSEC iQ-F series CPU module	FX5U-32MR/DS, FX5U-32MR/ES, FX5U-32MT/DS, FX5U-32MT/DSS, FX5U-32MT/ES, FX5U-32MT/ESS, FX5U-64MR/DS, FX5U-64MR/ES, FX5U-64MT/DS, FX5U-64MT/DSS, FX5U-64MT/ES, FX5U-64MT/ESS, FX5U-80MR/DS, FX5U-80MR/ES, FX5U-80MT/DS, FX5U-80MT/DSS, FX5U-80MT/ES, FX5U-80MT/ESS, FX5UC-32MR/DS-TS, FX5UC-32MT/D, FX5UC-32MT/DSS, FX5UC-32MT/DSS-TS, FX5UC-32MT/DS-TS, FX5UC-64MT/D, FX5UC-64MT/DSS, FX5UC-96MT/D, FX5UC-96MT/DSS
MELSEC iQ-R series CPU module	R00CPU, R01CPU, R02CPU, R04CPU, R04ENCPU, R08CPU, R08ENCPU, R16CPU, R16ENCPU, R32CPU, R32ENCPU, R120CPU, R120ENCPU

3 CHANGEOVER PERIOD

For models manufactured between December 2021 and February 2022, transcription type stickers had been put on the packaging boxes.

For models manufactured on or after March 2022, sealing stickers with strong adhesive have been put on the packaging boxes.

REVISIONS

Version	Date of Issue	Revision
A	November 2021	First edition
B	February 2022	Added the description about No.2 sealing sticker.
C	February 2024	Added the description about the changes of specifications of packaging boxes for the MELSEC iQ-R series CPU module. Deleted the description about the transcription type stickers (No.1) from Section 1.2.

TRADEMARKS

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